



# *Project XYZ Design Assumptions*

**Rev 0.1  
8/10/07**

- **Overview of the key expectations for the project. This is a summary sheet for the project.**

- **XXX Process**
  - **Process options (# metals, analog etc)**
  
- **I/O Plans**
  - **# Pins**
  - **Library(ies) to be used**
  - **Any Pad development needs**
  - **ESD & Latchup requirements.**

- **Digital Flow & technology files**
- **Analog Flow & PDK**
- **Which checklist or design traveler to be used.**
- **Any tool or flow development should go here.**
- **Top level validation strategy for mixed signal designs.**
- **Temperature and voltage simulation targets.**

- **Module size assumptions.**
- **Staggered or Inline pads. Pad pitch.**

- **Bullets for each major design activity to be completed. This is likely to be multiple pages.**
- **Evolutionary or revolutionary chip design.**
  - **If evolutionary note changes from starting point design.**
- **Module xxx from yyy**
  - **Modified by ...**
- **Specific new design activity**

- **Modules assumed to be reusable out of this projects.**
  - **Module xxx**
  - **Module yyy**
- **Patents**
  - **List any assumed patents here.**

- **Identify each risk along with mitigation strategy(ies)**

- **Die Size = (Less scribe)**
- **Tapeout Date:**
- **Resources: List by name**